

Sheet 1 of 1

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| Form PTO-1449 U.S. Department of Commerce (Rev. 8-88) Patent and Trademark Office INFORMATION DISCLOSURE CITATION (Use several sheets if necessary) | Attorney Docket No.: 1806.74544 | Serial No.: 10/566,070 |
| | Applicant: Pierre-Ernest BERNSTEIN et al. | |
| | Filing Date: January 26, 2006 | Group: 2862 |

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| Examiner /Jun Li/ | Date Considered 10/22/2008 |
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*Examiner:

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